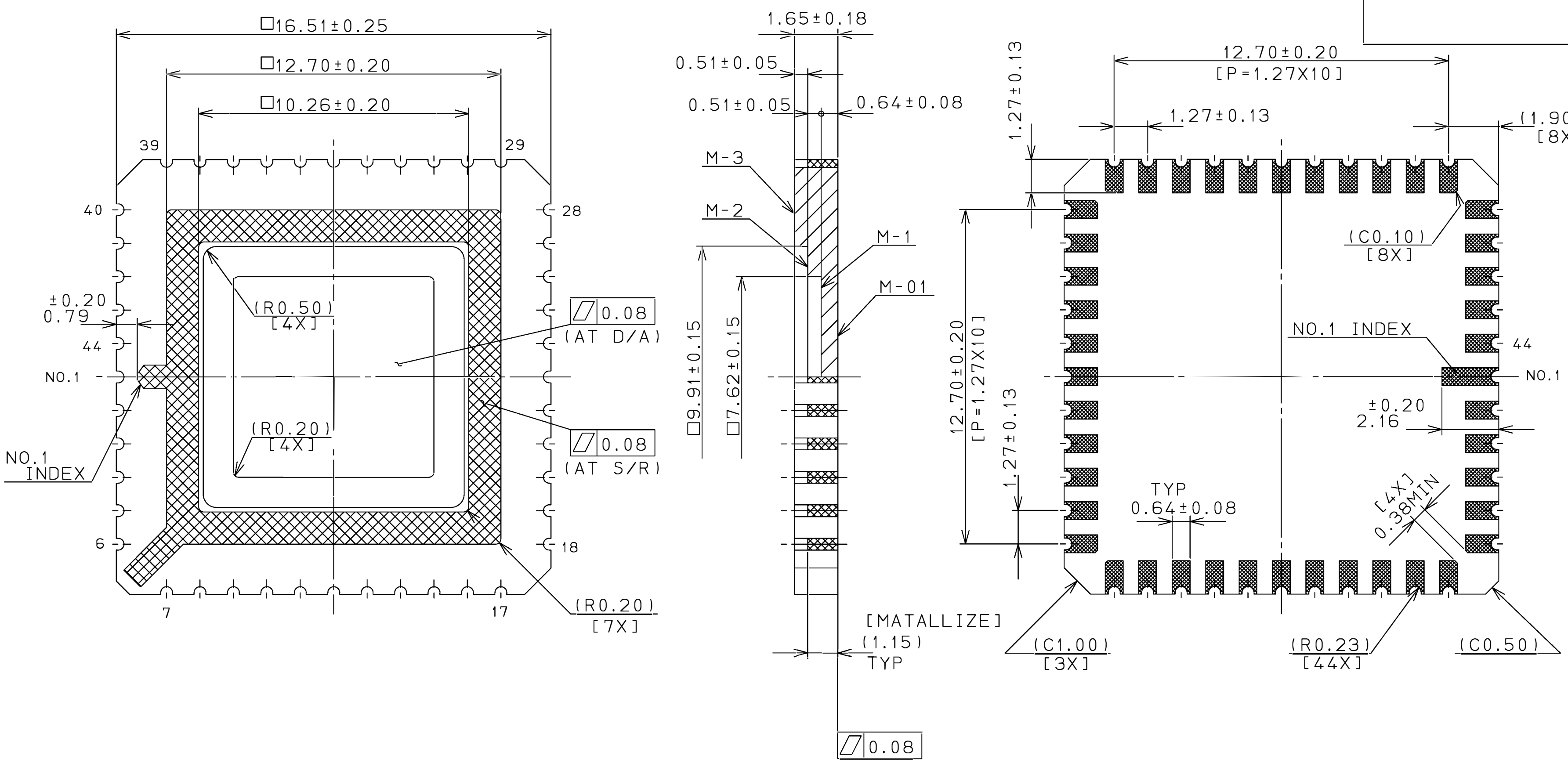
LCC04443

NTK

LATEST REVISION'S DESCRIPTION



NOTES: 1. GOLD PLATE 1.5μm MIN OVER 2.0μm MIN NICKEL.

2. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD.
SEAL RING ISOLATED.

3. NTK SPEC YS-1009 SHALL APPLY.

Item	N a m e	Material	Description
③			
②			
①	CERAMIC	BA-916	

Rev.	Description	Date
φ	NEW DRAWING	JUN.-01-2022

UNLESS OTHERWISE SPECIFIED
TOLERANCES: ± 1 %
N. L. T. 1 DECIMALS X.X ±0.25
2 DECIMALS X.X X ±0.13

CUSTOMER NTK OPEN
DWG NO.

DRAWN A.OKADA
CHECKED J.TSUCHIYA
APPROVED H.MIYAMOTO
UNIT MM
SCALE /

NGK SPARK PLUG CO., LTD.
TITLE 44 LD CHIP CARRIER
DWG NO. IRK44F1-5315D

MODIFIED DWG NO.

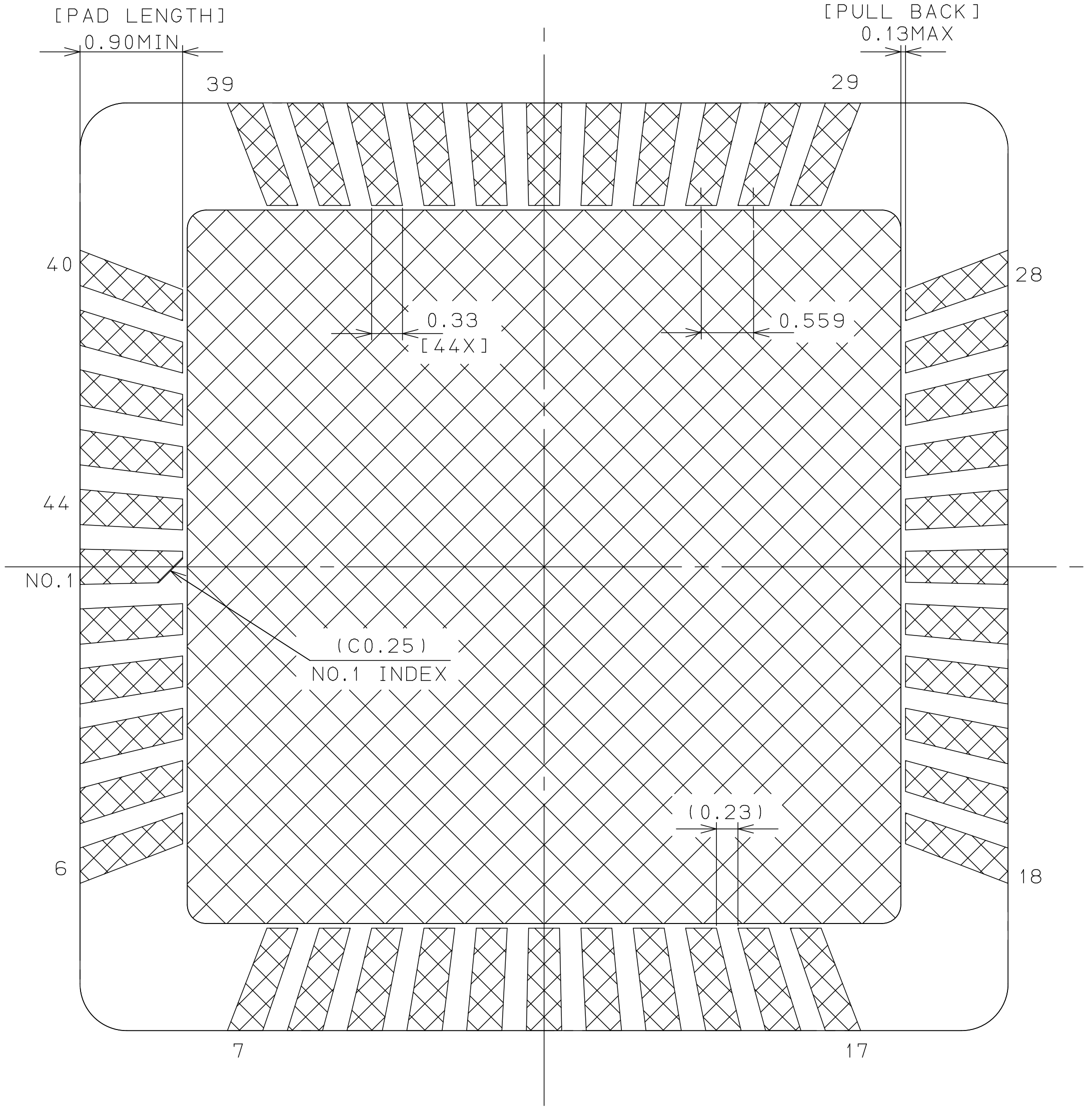
PART NO.

SHEET 1 OF 2

LCC04443

NTK

LATEST REVISION'S DESCRIPTION



B/G PADS DETAIL

Rev.	Description	Date
ϕ	NEW DRAWING	JUN.-01 -2022

UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1 % N. L. T. 1 DECIMALS X.X ±0.25 2 DECIMALS X.XX ±0.13	DRAWN A.OKADA CHECKED J.TSUCHIYA	NGK SPARK PLUG CO., LTD.
CUSTOMER NTK OPEN DWG NO.	APPROVED H.MIYAMOTO UNIT MM SCALE /	TITLE B/G PADS DETAIL DWG NO. IRK44F1-5315D

MODIFIED DWG NO.	

PART NO.	SHEET 2 OF 2